

## Scope

The conference will provide a forum for presenting current research and for discussions of future developments related to reliability and stress-induced phenomena in nanoelectronics. Stresses arising in metal structures and surrounding dielectric materials due to novel process steps and advanced materials can lead to degradation and failure of micro- and nanoelectronic products, and therefore, they bring new challenges for process integration, design optimization and reliability.

**Topics:** <http://irsp2016.malab.com/>

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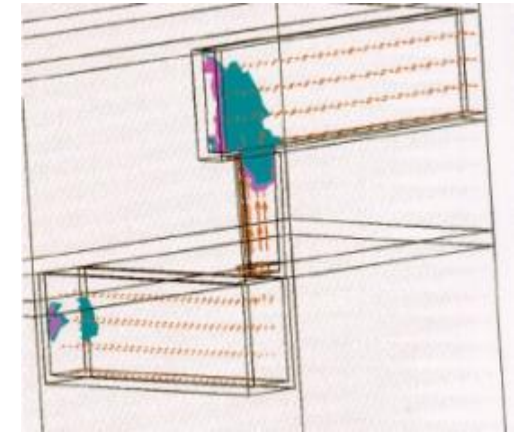
**AXO DRESDEN GmbH**  
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## Invited Speakers

- Andreas Aal, Volkswagen, Wolfsburg, Germany
- Andre Clausner, Fraunhofer IKTS Dresden, Germany
- Hajdin Ceric, University Vienna, Austria
- Reinhold Dauskardt, Stanford University, Palo Alto/CA, US
- Christoph Eberl, Fraunhofer IWM Freiburg, Germany
- Reyes Elizalde, Ceit, San Sebastian, Spain
- Ude Hangen, Hysitron, Aachen, Germany
- Ellen Hieckmann, TU Dresden, Germany
- Paul Ho, UT Austin/TX, US
- Tengfei Jiang, University of Central Florida/FL, US
- Shoji Kamiya, Nagoya Institute of Technology, Japan
- Christoph Kirchlechner, Max-Planck-Institut Düsseldorf, Germany
- Armen Kteyan, Mentor Graphics, Fremont/CA, US
- Han Li, Intel, Portland/OR, US
- Jim Lloyd, SUNY Albany/NY, US
- Sven Niese, AXO Dresden, Germany
- Cev Noyan, Columbia University/NY, US
- Thomas Nuytten, IMEC Leuven, Belgium
- Henry Proudhon, MINES ParisTech, France
- Han-Ping Pu, TSMC, Taiwan
- Manfred Reiche, Max-Planck-Institut Halle, Germany
- Valeriy Sukharev, Mentor Graphics, Fremont/CA, US
- Olivier Thomas, Aix Marseille University, France
- Dietmar Vogel, Fraunhofer ENAS Chemnitz, Germany
- Xiaopeng Xu, Synopsys, Mountain View/CA, US
- Wenbing Yun, Sigray, Concord/CA, US

## 3<sup>rd</sup> Announcement

### **14<sup>th</sup> International Conference Reliability and Stress-Related Phenomena in Nanoelectronics – Experiment and Simulation ("Stress Workshop")**



Courtesy of Valeriy Sukharev

**May 30 – June 1, 2016**  
**Bad Schandau, Germany**  
<http://irsp2016.malab.com/>

**Conference management:**  
**Innotec21 GmbH**

## Co-Chairs

- Ehrenfried Zschech, Fraunhofer IKTS, Dresden, Germany
- Paul Ho, UT Austin/TX, US
- Jon Molina, IMDEA Materials, Madrid, Spain
- Tony Oates, TSMC, Hsinchu, Taiwan
- Valeriy Sukharev, Mentor Graphics, Fremont/CA, US

## Scientific Committee

- Martin Gall, Fraunhofer IKTS, Dresden, Germany (co-chair)
- C. K. Hu, IBM Yorktown Heights/NY, US (co-chair)
- Bob Rosenberg, IBM Yorktown Heights/NY, US (co-chair)
- Andreas Aal, Volkswagen, Wolfsburg, Germany
- Reinhold Dauskardt, Stanford University, Palo Alto/CA, US
- Alex Dommann, EMPA, Switzerland
- Junichi Koike, Tohoku University, Sendai, Japan
- Zhiyong Ma, Intel, Hillsboro/OR, US
- Mireille Mouis, CNRS, IMEP-LaHC, Grenoble, France
- Tomoji Nakamura, Fujitsu, Tokyo, Japan
- Alexander Narr, GLOBALFOUNDRIES, Dresden, Germany
- Jungwoo Pyun, Samsung, Korea
- Riko Radojic, San Diego/CA, US
- Marco Sebastiani, University Rome, Italy
- Olivier Thomas, Aix Marseille Université, France
- King-Ning Tu, UCLA, Los Angeles/CA, US
- Xiaopeng Xu, Synopsys, Mountain View/CA, US

## Registration

### Registration fee

The registration fee includes technical sessions, 3 days lunches and coffee breaks, a conference dinner, a hiking tour into the breathtaking Elbe sandstone region and the abstract booklet.

- Early Registration – **Euro 400** (payment must be received by **January 31, 2016**)
- Late Registration – **Euro 480** (payments received after **January 31, 2016**, and on the conference site)

### Form of Payment

Payments can be made by wire transfer or credit card. For more information, please see our conference web page <http://irsp2016.malab.com/>.

### Register Now

The number of participants will be limited in order to maintain the intimate atmosphere of the conference. Please provide your registration through the form under the "Registration" heading of our conference web page <http://irsp2016.malab.com/>.

## Conference Contact

Ehrenfried Zschech  
Phone +49 351 88815 543  
Email [ehrenfried.zschech@ikts.fraunhofer.de](mailto:ehrenfried.zschech@ikts.fraunhofer.de)

## Late Papers

One-page abstracts for late papers have to be sent directly to the Chair: [ehrenfried.zschech@ikts.fraunhofer.de](mailto:ehrenfried.zschech@ikts.fraunhofer.de)  
Abstracts will be published in the conference abstract book as submitted.

## Journal Papers

Selected papers will be published in IEEE Transactions on Device and Materials Reliability (TDMR) and in Advanced Engineering Materials (AEM). The deadline for submission of manuscripts will be **July 31, 2016**.

## Conference venue

Hotel Elbresidenz Bad Schandau, near Dresden, Germany:  
<http://www.elbresidenz-bad-schandau.de/en/start-page/>

## Accommodation

A block of rooms is reserved at the conference hotel. There are several other hotels (different price categories) available in walking distance. Reservations must be made by **Mai 15, 2016**, to guarantee a room. Please identify yourself as being with the **IRSP 2016** to get a room from the reserved block of rooms.